



michelle.zhou@mdpi.com on behalf of Editorial Office <electronics@mdpi.com>

To: Wahyu Caesarendra <wahyu.caesarendra@ubd.edu.bn>

Cc: Daniel Sutopo Pamungkas +4 others



Mon 9/30/2019 4:43 PM

Dear Dr. Caesarendra,

Thank you very much for uploading the following manuscript to the MDPI submission system. One of our editors will be in touch with you soon.

Journal name: Electronics

Manuscript ID: electronics-618052

Type of manuscript: Review

Title: Overview Types of Lower Limb Exoskeletons

Authors: Daniel S Pamungkas, Wahyu Caesarendra *, Hendawan Soebakti, Riska Analia, HS Susanto

Received: 30 September 2019

E-mails: daniel@polibatam.ac.id, wahyu.caesarendra@ubd.edu.bn, hendawan@polibatam.ac.id, riskaanalia@polibatam.ac.id, susanto@polibatam.ac.id

Submitted to section: Artificial Intelligence,

https://www.mdpi.com/journal/electronics/sections/Artificial_Intell

Intelligent Electronic Devices

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You can follow progress of your manuscript at the following link (login required):

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The following points were confirmed during submission:



Judy Jia <judy.jia@mdpi.com>

To: ○ Wahyu Caesarendra <wahyu.caesarendra@ubd.edu.bn>

Cc: ○ Judy Jia <judy.jia@mdpi.com>; ○ Daniel Sutopo Pamungkas +4 others



Mon 9/30/2019 5:38 P

Dear Dr. Caesarendra,

Your manuscript has been assigned to Judy Jia for further processing who will act as a point of contact for any questions related to your paper.

Journal: Electronics

Manuscript ID: electronics-618052

Title: Overview Types of Lower Limb Exoskeletons

Authors: Daniel S Pamungkas , Wahyu Caesarendra *, Hendawan Soebakti , Riska Analia , HS Susanto

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You can find it here:

https://susy.mdpi.com/user/manuscripts/review_info/671b5f63c3eb6f10f2ed4a975747ac3c

Best regards,

Ms. Judy Jia, MEng

Assistant Editor

Email: judy.jia@mdpi.com

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[Electronics] Manuscript ID: electronics-618052 - Manuscript Resubmitted



judy.jia@mdpi.com on behalf of Submission System <submission@mdpi.com>

Sun 10/27/2019 9:11 AM

To: Wahyu Caesarendra <wahyu.caesarendra@ubd.edu.bn>
Cc: Daniel Sutopo Pamungkas; Hendawan Soebhakti; Riska Analia; Susanto

Dear Dr. Caesarendra,

Thank you very much for resubmitting the modified version of the following manuscript:

Manuscript ID: electronics-618052
Type of manuscript: Review
Title: Overview Types of Lower Limb Exoskeletons
Authors: Daniel S Pamungkas, Wahyu Caesarendra *, Hendawan Soebakti, Riska Analia, Susanto Susanto
Received: 30 September 2019
E-mails: daniel@polibatam.ac.id, wahyu.caesarendra@ubd.edu.bn, hendawan@polibatam.ac.id, riskaanalia@polibatam.ac.id, susanto@polibatam.ac.id
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A member of the editorial office will be in touch with you soon regarding progress of the manuscript.

Kind regards,

MDPI

[Electronics] Manuscript ID: electronics-618052 - Major Revisions (Deadline 28 October 2019)



Judy Jia <judy.jia@mdpi.com>

Sun 10/27/2019 9:14 AM

To: Dr Wahyu Caesarendra <wahyu.caesarendra@ubd.edu.bn>
Cc: electronics@mdpi.com; Daniel Sutopo Pamungkas; Hendawan Soebhakti +2 others

Dear Dr. Caesarendra,

Thank you for your letter. I will help to upload your files on the system and process it soon.

Please feel free to let me know if any questions.

Kind regards,
Ms. Judy Jia
Assistant Editor
Email: judy.jia@mdpi.com
Twitter: @ElectronicsMDPI
Electronics (IF 1.764, <http://www.mdpi.com/journal/Electronics>)
Electronics Travel Award 2020 and Electronics Young Investigator Award 2020 are open for applications now:
<https://www.mdpi.com/journal/electronics/awards>



Judy Jia <judy.jia@mdpi.com>



To: Wahyu Caesarendra <wahyu.caesarendra@ubd.edu.bn>

Sun 10/27/2019 9:14 AM

Cc: Daniel Sutopo Pamungkas; Hendawan Soebhakti; Riska Analia; Susanto +1 other

Dear Dr. Caesarendra,

Thank you very much for providing the revised version of your paper:

Manuscript ID: electronics-618052

Type of manuscript: Review

Title: Overview Types of Lower Limb Exoskeletons

Authors: Daniel S Pamungkas, Wahyu Caesarendra *, Hendawan Soebhakti, Riska

Analia, Susanto Susanto

Received: 30 September 2019

E-mails: daniel@polibatam.ac.id, wahyu.caesarendra@ubd.edu.bn,

hendawan@polibatam.ac.id, riskaanalia@polibatam.ac.id, susanto@polibatam.ac.id

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We will continue processing your paper and will keep you informed about the submission status.

Kind regards,

Ms. Judy Jia, MEng
Assistant Editor



Judy Jia <judy.jia@mdpi.com>



To: Wahyu Caesarendra <wahyu.caesarendra@ubd.edu.bn>

Mon 10/28/2019 9:07 AM

Cc: Daniel Sutopo Pamungkas; Hendawan Soebhakti; Riska Analia +3 others

Dear Dr. Caesarendra,

We are pleased to inform you that the following paper has been officially accepted for publication:

Manuscript ID: electronics-618052

Type of manuscript: Review

Title: Overview Types of Lower Limb Exoskeletons

Authors: Daniel S Pamungkas, Wahyu Caesarendra *, Hendawan Soebhakti, Riska Analia, Susanto Susanto

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E-mails: daniel@polibatam.ac.id, wahyu.caesarendra@ubd.edu.bn,

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We will now make the final preparations for publication, then return the manuscript to you for your approval.

If, however, extensive English edits are required to your manuscript, we will need to return the paper requesting improvements throughout.